Dkt. No.: OP-093000122

AMENDMENTS TO THE CLAIMS:

1. (Currently Amended) A mesh structure disposed between a plurality of anode units and cathode units of a tetraode field emission display, comprising:

a first conductive layer to serve as a converging electrode layer having a proximal surface facing the anode units and a distal surface opposing to the proximal surface, the first conductive layer comprising a plurality of first apertures extending therethrough;

a glass plate formed on the proximal surface of the first conductive layer to serve as a spacer, the glass plate including a plurality of second apertures extending therethrough and each second aperture covering an opening range of a row or a column of the first apertures;

an insulation layer formed on the distal surface of the first conductive layer; and a second conductive layer formed on the insulation layer to serve as a gate electrode layer, the second conductive layer having a proximal surface facing the cathode units and a distal surface opposing to the proximal surface, wherein the second conductive layer includes a plurality of third apertures extending therethrough and aligned with the first and second apertures, and each third aperture covers an opening range of a row or a column of the first apertures,

wherein a plurality of isolation slits extend across the second conductive layer so that a pair of conductive strips are formed at two elongate sides of each third aperture, each pair of the conductive strips constructs an independent conductive path to be biased with a potential and a gate operative to drain electron from the cathode unit between the pair of conductive strips is formed.

Claims 2-10 (Cancelled)

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11. (Withdrawn) A method of fabricating a mesh structure mounted between an anode plate and a cathode plate of a tetra-polar field-emission display, comprising:

providing a first conductive plate;

forming a plurality of first apertures extending through the first conductive plate; providing a glass plate to server as a spacer;

forming a plurality of second apertures extending through the glass plate;

temporally attaching the glass plate to one side of the first conductive plate with the second apertures aligned with the first apertures;

providing an insulation layer formed on the other side of the first conductive plate; providing a second conductive plate;

forming a plurality of third apertures extending through the second conductive plate; temporally attaching the second conductive plate to the insulation layer with the third apertures aligned with the first and second apertures; and

permanently stacking the glass plate, the first conductive plate, the insulation plate and the second conductive plate to form the mesh structure.

- 12. (Withdrawn) The method of Claim 11, wherein the step of temporally attaching the glass plate to the first conductive plate includes applying an ultra-violet glue therebetween.
- 13. (Withdrawn) The method of Claim 11, wherein the step of temporally attaching the second conductive plate to the insulation layer includes applying an ultra-violet glue therebetween.
- 14. (Withdrawn) The method of Claim 11, wherein the step of permanently stacking the glass plate, the first conductive plate, the insulation plate and the second conductive plate includes a high-temperature sintering process.

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15. (Withdrawn) The method of Claim 11, further comprising providing the first and second conductive layer fabricated from a material having a thermal expansion coefficient similar to that of the anode plate and the cathode plate.

- 16. (Withdrawn) The method of Claim 11, further comprising providing the glass plate having a thermal expansion coefficient similar to that of the anode plate and the cathode plate.
 - 17. (Withdrawn) The method of Claim 11, wherein the insulation layer is a glass glue.
- 18. (Previously Presented) The mesh structure of Claim 1, wherein each first aperture is aligned with a corresponding anode unit with a phospher layer and cathode unit with an emission layer.